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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Obsolete
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I ² C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	30-LSSOP (0.240", 6.10mm Width)
Supplier Device Package	30-LSSOP
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f100acasp-v0

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Table 1-1. List of Ordering Part Numbers

(8/12)

Pin count	Package	Data flash	Fields of	Ordering Part Number
			Application Note	
64 pins	64-pin plastic LQFP	Mounted	Α	R5F100LCAFA#V0, R5F100LDAFA#V0,
	(12 × 12 mm, 0.65			R5F100LEAFA#V0, R5F100LFAFA#V0,
	mm pitch)			R5F100LGAFA#V0, R5F100LHAFA#V0,
				R5F100LJAFA#V0, R5F100LKAFA#V0, R5F100LLAFA#V0
				R5F100LCAFA#X0, R5F100LDAFA#X0,
				R5F100LEAFA#X0, R5F100LFAFA#X0,
			D	R5F100LGAFA#X0, R5F100LHAFA#X0,
				R5F100LJAFA#X0, R5F100LKAFA#X0, R5F100LLAFA#X0
				R5F100LCDFA#V0, R5F100LDDFA#V0,
				R5F100LEDFA#V0, R5F100LFDFA#V0,
				R5F100LGDFA#V0, R5F100LHDFA#V0,
				R5F100LJDFA#V0, R5F100LKDFA#V0, R5F100LLDFA#V0
			G	R5F100LCDFA#X0, R5F100LDDFA#X0,
				R5F100LEDFA#X0, R5F100LFDFA#X0,
				R5F100LGDFA#X0, R5F100LHDFA#X0,
				R5F100LJDFA#X0, R5F100LKDFA#X0, R5F100LLDFA#X0
				R5F100LCGFA#V0, R5F100LDGFA#V0,
				R5F100LEGFA#V0, R5F100LFGFA#V0
				R5F100LCGFA#X0, R5F100LDGFA#X0,
				R5F100LEGFA#X0, R5F100LFGFA#X0
				R5F100LGGFA#V0, R5F100LHGFA#V0,
				R5F100LJGFA#V0
				R5F100LGGFA#X0, R5F100LHGFA#X0,
				R5F100LJGFA#X0
		Not	Α	R5F101LCAFA#V0, R5F101LDAFA#V0,
		mounted		R5F101LEAFA#V0, R5F101LFAFA#V0,
				R5F101LGAFA#V0, R5F101LHAFA#V0,
				R5F101LJAFA#V0, R5F101LKAFA#V0, R5F101LLAFA#V0
				R5F101LCAFA#X0, R5F101LDAFA#X0,
				R5F101LEAFA#X0, R5F101LFAFA#X0,
			D	R5F101LGAFA#X0, R5F101LHAFA#X0,
				R5F101LJAFA#X0, R5F101LKAFA#X0, R5F101LLAFA#X0
				R5F101LCDFA#V0, R5F101LDDFA#V0,
				R5F101LEDFA#V0, R5F101LFDFA#V0,
				R5F101LGDFA#V0, R5F101LHDFA#V0,
				R5F101LJDFA#V0, R5F101LKDFA#V0, R5F101LLDFA#V0
				R5F101LCDFA#X0, R5F101LDDFA#X0,
				R5F101LEDFA#X0, R5F101LFDFA#X0,
				R5F101LGDFA#X0, R5F101LHDFA#X0,
				R5F101LJDFA#X0, R5F101LKDFA#X0, R5F101LLDFA#X0

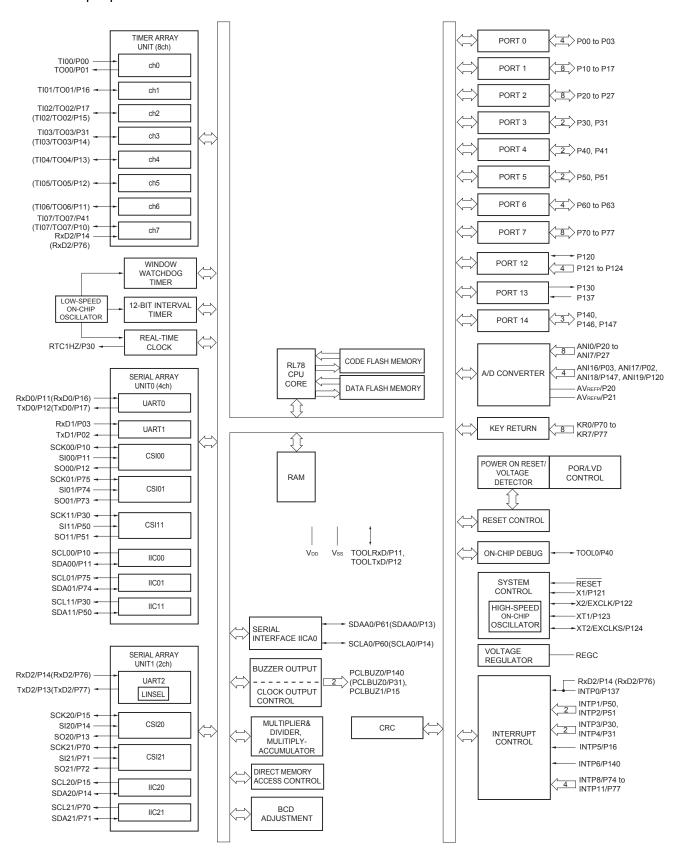
Note For the fields of application, refer to Figure 1-1 Part Number, Memory Size, and Package of RL78/G13.

Caution The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.



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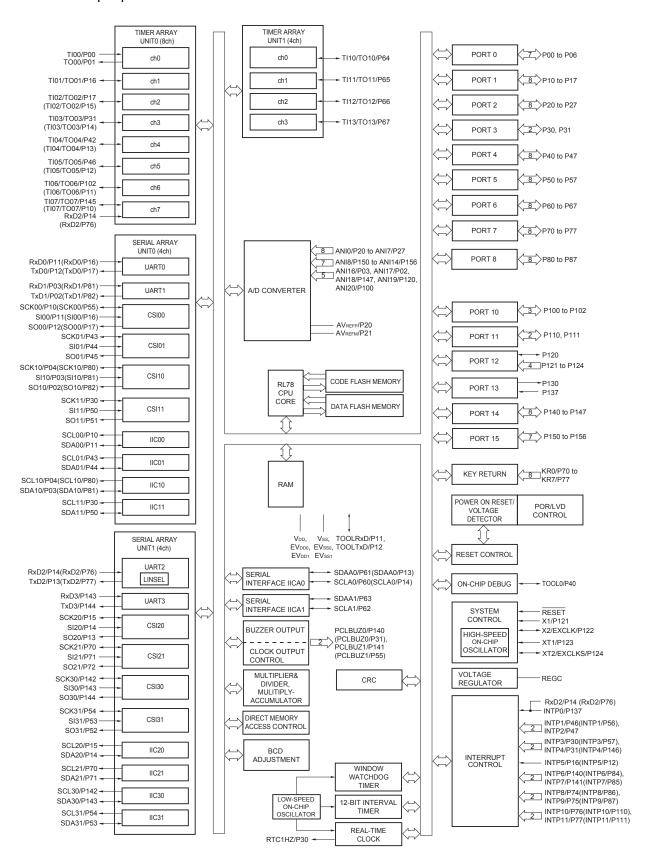
1.5.10 52-pin products



Remark Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR) in the RL78/G13 User's Manual.

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1.5.13 100-pin products



Remark Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR) in the RL78/G13 User's Manual.

2.2 Oscillator Characteristics

2.2.1 X1, XT1 oscillator characteristics

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.6 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{Vss} = 0 \text{ V})$

Parameter	Resonator	Conditions	MIN.	TYP.	MAX.	Unit
X1 clock oscillation	Ceramic resonator/	$2.7~V \leq V_{\text{DD}} \leq 5.5~V$	1.0		20.0	MHz
frequency (fx) ^{Note}	crystal resonator	$2.4~V \leq V_{DD} < 2.7~V$	1.0		16.0	MHz
		$1.8~V \leq V_{DD} < 2.4~V$	1.0		8.0	MHz
		$1.6~V \leq V_{DD} < 1.8~V$	1.0		4.0	MHz
XT1 clock oscillation frequency (fx) ^{Note}	Crystal resonator		32	32.768	35	kHz

Note Indicates only permissible oscillator frequency ranges. Refer to AC Characteristics for instruction execution time. Request evaluation by the manufacturer of the oscillator circuit mounted on a board to check the oscillator characteristics.

Caution Since the CPU is started by the high-speed on-chip oscillator clock after a reset release, check the X1 clock oscillation stabilization time using the oscillation stabilization time counter status register (OSTC) by the user. Determine the oscillation stabilization time of the OSTC register and the oscillation stabilization time select register (OSTS) after sufficiently evaluating the oscillation stabilization time with the resonator to be used.

Remark When using the X1 oscillator and XT1 oscillator, refer to 5.4 System Clock Oscillator.

2.2.2 On-chip oscillator characteristics

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.6 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{Vss} = 0 \text{ V})$

Oscillators	Parameters		Conditions	MIN.	TYP.	MAX.	Unit
High-speed on-chip oscillator clock frequency Notes 1, 2	fін			1		32	MHz
High-speed on-chip oscillator		–20 to +85 °C	$1.8~V \leq V_{DD} \leq 5.5~V$	-1.0		+1.0	%
clock frequency accuracy			$1.6~V \leq V_{DD} < 1.8~V$	-5.0		+5.0	%
		–40 to −20 °C	$1.8~V \leq V_{DD} \leq 5.5~V$	-1.5		+1.5	%
			$1.6~V \leq V_{DD} < 1.8~V$	-5.5		+5.5	%
Low-speed on-chip oscillator clock frequency	fıL				15		kHz
Low-speed on-chip oscillator clock frequency accuracy				-15		+15	%

Notes 1. High-speed on-chip oscillator frequency is selected by bits 0 to 3 of option byte (000C2H/010C2H) and bits 0 to 2 of HOCODIV register.

2. This indicates the oscillator characteristics only. Refer to AC Characteristics for instruction execution time.

2.3 DC Characteristics

2.3.1 Pin characteristics

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.6 \text{ V} \le \text{EV}_{DD0} = \text{EV}_{DD1} \le \text{V}_{DD} \le 5.5 \text{ V}, \text{Vss} = \text{EV}_{SS0} = \text{EV}_{SS1} = 0 \text{ V}) (1/5)$

Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, high ^{Note 1}	Іон1	Per pin for P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147	$1.6~V \le EV_{DD0} \le 5.5~V$			-10.0 Note 2	mA
		Total of P00 to P04, P07, P32 to P37,	$4.0~V \leq EV_{DD0} \leq 5.5~V$			-55.0	mA
		P125 to P127, P130, P140 to P145 (When duty ≤ 70% Note 3)	$2.7~V \leq EV_{DD0} < 4.0~V$			-10.0	mA
			$1.8~V \leq EV_{DD0} < 2.7~V$			-5.0	mA
			$1.6~V \leq EV_{DD0} < 1.8~V$			-2.5	mA
		Total of P05, P06, P10 to P17, P30, P31,				-80.0	mA
		P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100, P101, P110 to	$2.7~V \leq EV_{DD0} < 4.0~V$			-19.0	mA
		P117, P146, P147	$1.8~V \leq EV_{DD0} < 2.7~V$			-10.0	mA
		(When duty $\leq 70\%$ Note 3)	$1.6~V \leq EV_{DD0} < 1.8~V$			-5.0	mA
		Total of all pins (When duty ≤ 70% Note 3)	$1.6~V \leq EV_{DD0} \leq 5.5~V$			-135.0 Note 4	mA
	І он2	Per pin for P20 to P27, P150 to P156	$1.6~V \leq V_{DD} \leq 5.5~V$			-0.1 Note 2	mA
		Total of all pins (When duty ≤ 70% Note 3)	$1.6~V \leq V_{DD} \leq 5.5~V$			-1.5	mA

- **Notes 1**. Value of current at which the device operation is guaranteed even if the current flows from the EV_{DD0}, EV_{DD1}, V_{DD} pins to an output pin.
 - 2. However, do not exceed the total current value.
 - 3. Specification under conditions where the duty factor $\leq 70\%$.

The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

• Total output current of pins = $(IOH \times 0.7)/(n \times 0.01)$

<Example> Where n = 80% and loh = -10.0 mA

Total output current of pins = $(-10.0 \times 0.7)/(80 \times 0.01) \cong -8.7$ mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

4. The applied current for the products for industrial application (R5F100xxDxx, R5F101xxDxx, R5F100xxGxx) is -100 mA.

Caution P00, P02 to P04, P10 to P15, P17, P43 to P45, P50, P52 to P55, P71, P74, P80 to P82, P96, and P142 to P144 do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.



 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.6 \text{ V} \le \text{EV}_{DD0} = \text{EV}_{DD1} \le \text{V}_{DD} \le 5.5 \text{ V}, \text{Vss} = \text{EV}_{SS0} = \text{EV}_{SS1} = 0 \text{ V})$ (3/5)

Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input voltage, high	V _{IH1}	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147		0.8EVDD0		EV _{DD0}	V
	V _{IH2}	P01, P03, P04, P10, P11, P13 to P17, P43, P44, P53 to P55,	TTL input buffer 4.0 V ≤ EV _{DD0} ≤ 5.5 V	2.2		EV _{DD0}	V
		P80, P81, P142, P143	TTL input buffer $3.3 \text{ V} \le \text{EV}_{\text{DD0}} < 4.0 \text{ V}$	2.0		EV _{DD0}	V
V _{IH3}			TTL input buffer 1.6 V ≤ EV _{DD0} < 3.3 V	1.5		EV _{DD0}	V
	V _{IH3}	P20 to P27, P150 to P156	0.7V _{DD}		V _{DD}	٧	
	V _{IH4}	P60 to P63	0.7EV _{DD0}		6.0	٧	
	V _{IH5}	P121 to P124, P137, EXCLK, EXCL	KS, RESET	0.8V _{DD}		V _{DD}	٧
Input voltage, low	V _{IL1}	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147	,	0		0.2EV _{DD0}	V
	V _{IL2}	P01, P03, P04, P10, P11, P13 to P17, P43, P44, P53 to P55,	TTL input buffer 4.0 V ≤ EV _{DD0} ≤ 5.5 V	0		0.8	V
		P80, P81, P142, P143	TTL input buffer 3.3 V ≤ EV _{DD0} < 4.0 V	0		0.5	V
			TTL input buffer 1.6 V ≤ EV _{DD0} < 3.3 V	0		0.32	V
	VIL3	P20 to P27, P150 to P156		0		0.3V _{DD}	٧
	V _{IL4}	P60 to P63		0		0.3EV _{DD0}	٧
	V _{IL5}	P121 to P124, P137, EXCLK, EXCL	KS, RESET	0		0.2V _{DD}	٧

Caution The maximum value of V_{IH} of pins P00, P02 to P04, P10 to P15, P17, P43 to P45, P50, P52 to P55, P71, P74, P80 to P82, P96, and P142 to P144 is EV_{DD0}, even in the N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

- Notes 1. Total current flowing into VDD, EVDDO, and EVDD1, including the input leakage current flowing when the level of the input pin is fixed to VDD, EVDDO, and EVDD1, or Vss, EVSSO, and EVSS1. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
 - 2. When high-speed on-chip oscillator and subsystem clock are stopped.
 - 3. When high-speed system clock and subsystem clock are stopped.
 - **4.** When high-speed on-chip oscillator and high-speed system clock are stopped. When AMPHS1 = 1 (Ultra-low power consumption oscillation). However, not including the current flowing into the 12-bit interval timer and watchdog timer.
 - **5.** Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V \leq VDD \leq 5.5 V@1 MHz to 32 MHz

 $2.4 \text{ V} \le V_{DD} \le 5.5 \text{ V} @ 1 \text{ MHz}$ to 16 MHz

LS (low-speed main) mode: $1.8 \text{ V} \le \text{V}_{DD} \le 5.5 \text{ V}@1 \text{ MHz}$ to 8 MHz LV (low-voltage main) mode: $1.6 \text{ V} \le \text{V}_{DD} \le 5.5 \text{ V}@1 \text{ MHz}$ to 4 MHz

- Remarks 1. fmx: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
 - 2. fin: High-speed on-chip oscillator clock frequency
 - **3.** fsub: Subsystem clock frequency (XT1 clock oscillation frequency)
 - 4. Except subsystem clock operation, temperature condition of the TYP. value is TA = 25°C

(3) During communication at same potential (CSI mode) (master mode, SCKp... internal clock output) $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.6 \text{ V} \leq \text{EV}_{\text{DD0}} = \text{EV}_{\text{DD1}} \leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}, \text{Vss} = \text{EV}_{\text{SS0}} = \text{EV}_{\text{SS1}} = 0 \text{ V})$

Parameter	Symbol	C	Conditions	HS (high main)	•	LS (low main)	•	LV (low- main)	-voltage Mode	Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp cycle time	tkcy1	tксү1 ≥ 4/fс∟к	$2.7~V \leq EV_{DD0} \leq 5.5$ V	125		500		1000		ns
			$2.4~V \leq EV_{DD0} \leq 5.5$ V	250		500		1000		ns
			$1.8~V \le EV_{DD0} \le 5.5$ V	500		500		1000		ns
			$1.7~V \le EV_{DD0} \le 5.5$ V	1000		1000		1000		ns
			$1.6~V \le EV_{DD0} \le 5.5$ V	_		1000		1000		ns
SCKp high-/low-level width	tkhi, tkli	4.0 V ≤ EV _D	00 ≤ 5.5 V	tксү1/2 – 12		tксу1/2 — 50		tксү1/2 – 50		ns
		$2.7 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$ $2.4 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$		tксү1/2 – 18		tксу1/2 — 50		tксү1/2 – 50		ns
				tксү1/2 – 38		tксу1/2 — 50		tксү1/2 — 50		ns
		1.8 V ≤ EV _D	00 ≤ 5.5 V	tксү1/2 — 50		tксү1/2 — 50		tксү1/2 – 50		ns
		1.7 V ≤ EV _D	00 ≤ 5.5 V	tксу1/2 — 100		tксу1/2 — 100		tксу1/2 — 100		ns
		1.6 V ≤ EVD	₀₀ ≤ 5.5 V	_		tксу1/2 — 100		tксу1/2 — 100		ns
SIp setup time	tsıĸı	4.0 V ≤ EV _{DI}	00 ≤ 5.5 V	44		110		110		ns
(to SCKp↑)		2.7 V ≤ EV _{DI}	00 ≤ 5.5 V	44		110		110		ns
		2.4 V ≤ EV _{DI}	00 ≤ 5.5 V	75		110		110		ns
		1.8 V ≤ EV _{DI}	oo ≤ 5.5 V	110		110		110		ns
		1.7 V ≤ EV _{DI}	oo ≤ 5.5 V	220		220		220		ns
		1.6 V ≤ EV _{DI}	oo ≤ 5.5 V	_		220		220		ns
SIp hold time	tksi1	1.7 V ≤ EV _{DI}	00 ≤ 5.5 V	19		19		19		ns
(from SCKp↑) Note 2		1.6 V ≤ EV _{DI}	00 ≤ 5.5 V	_		19		19		ns
Delay time from SCKp↓ to SOp	tkso1	$1.7 \text{ V} \le \text{EV}_{DI}$ $C = 30 \text{ pF}^{\text{Note}}$			25		25		25	ns
output Note 3		$1.6 \text{ V} \leq \text{EV}_{DI}$ $C = 30 \text{ pF}^{\text{Note}}$			_		25		25	ns

Notes 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

- 2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
- 3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
- 4. C is the load capacitance of the SCKp and SOp output lines.

Caution Select the normal input buffer for the SIp pin and the normal output mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

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(4) During communication at same potential (CSI mode) (slave mode, SCKp... external clock input) (2/2)

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.6 \text{ V} \le \text{EV}_{DD0} = \text{EV}_{DD1} \le \text{V}_{DD} \le 5.5 \text{ V}, \text{Vss} = \text{EV}_{SS0} = \text{EV}_{SS1} = 0 \text{ V})$ Parameter Symbo Conditions HS (high-speed LS (low-speed main) LV (low-voltage main) Unit main) Mode ı Mode Mode MIN. MIN. MAX. MIN. MAX. MAX. Slp setup time tsik2 $2.7 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$ $1/f_{MCK}+2$ 1/fmck+30 1/fmck+30 ns (to SCKp↑) Note 1 n $1.8~V \leq EV_{DD0} \leq 5.5~V$ 1/fмск+3 1/fмск+30 1/fмcк+30 ns 0 $1.7~V \leq EV_{DD0} \leq 5.5~V$ 1/fмск+4 $1/f_{MCK}+40$ $1/f_{MCK}+40$ ns 0 1/fмск+40 1/fмск+40 $1.6~V \leq EV_{\text{DD0}} \leq 5.5~V$ ns Slp hold time tks12 $1.8~V \leq EV_{DD0} \leq 5.5~V$ 1/fмск+3 1/fмcк+31 1/fмcк+31 ns (from SCKp↑) 1 $1.7~V \leq EV_{DD0} \leq 5.5~V$ 1/fмcк+ 1/fмск+ 1/fмcк+ ns 250 250 250 $1.6~V \leq EV_{\text{DD0}} \leq 5.5~V$ 1/fmck+ 1/fмcк+ ns 250 250 2/f_{MCK+} 2/f_{MCK+} Delay time tks02 C = 30 $2.7 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5$ 2/fmck+ ns pF Note 4 from SCKp↓ to 44 110 110 SOp output Note $2.4 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5$ 2/fmck+ 2/fмcк+ 2/fmck+ ns 110 75 110 2/fмск+ $1.8 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5$ 2/fмск+ 2/fмск+ ns 110 110 110 $1.7 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5$ 2/fmck+ 2/fmck+ 2/fмск+ ns 220 220 220 $1.6 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5$ 2/fмск+ 2/fмск+ ns

- **Notes 1.** When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to $SCKp\downarrow$ " when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
 - 2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
 - 3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
 - 4. C is the load capacitance of the SOp output lines.
 - 5. Transfer rate in the SNOOZE mode: MAX. 1 Mbps

Caution Select the normal input buffer for the SIp pin and SCKp pin and the normal output mode for the SOp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

- **Remarks 1.** p: CSI number (p = 00, 01, 10, 11, 20, 21, 30, 31), m: Unit number (m = 0, 1), n: Channel number (n = 0 to 3), g: PIM number (g = 0, 1, 4, 5, 8, 14)
 - 2. fmck: Serial array unit operation clock frequency

 (Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number,

 n: Channel number (mn = 00 to 03, 10 to 13))

2.8 Flash Memory Programming Characteristics

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.8 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{ Vss} = 0 \text{ V})$

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
CPU/peripheral hardware clock frequency	fclk	$1.8~V \leq V \text{dd} \leq 5.5~V$	1		32	MHz
Number of code flash rewrites	Cerwr	Retained for 20 years TA = 85°C	1,000			Times
Number of data flash rewrites		Retained for 1 years TA = 25°C		1,000,000		
		Retained for 5 years TA = 85°C	100,000			
		Retained for 20 years TA = 85°C	10,000			

Notes 1. 1 erase + 1 write after the erase is regarded as 1 rewrite.

- The retaining years are until next rewrite after the rewrite.
- 2. When using flash memory programmer and Renesas Electronics self programming library
- **3.** These are the characteristics of the flash memory and the results obtained from reliability testing by Renesas Electronics Corporation.

2.9 Dedicated Flash Memory Programmer Communication (UART)

$(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.8 \text{ V} \le \text{EV}_{DD0} = \text{EV}_{DD1} \le \text{V}_{DD} \le 5.5 \text{ V}, \text{Vss} = \text{EV}_{SS0} = \text{EV}_{SS1} = 0 \text{ V})$

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Transfer rate		During serial programming	115,200	_	1,000,000	bps

3. ELECTRICAL SPECIFICATIONS (G: INDUSTRIAL APPLICATIONS $T_A = -40$ to +105°C)

This chapter describes the following electrical specifications.

Target products G: Industrial applications $T_A = -40$ to +105°C R5F100xxGxx

- Cautions 1. The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.
 - 2. With products not provided with an EVDD0, EVDD1, EVSS0, or EVSS1 pin, replace EVDD0 and EVDD1 with VDD, or replace EVSS0 and EVSS1 with VSS.
 - 3. The pins mounted depend on the product. Refer to 2.1 Port Function to 2.2.1 Functions for each product.
 - 4. Please contact Renesas Electronics sales office for derating of operation under $T_A = +85^{\circ}C$ to $+105^{\circ}C$. Derating is the systematic reduction of load for the sake of improved reliability.

Remark When RL78/G13 is used in the range of $T_A = -40$ to +85°C, see CHAPTER 2 ELECTRICAL SPECIFICATIONS ($T_A = -40$ to +85°C).

There are following differences between the products "G: Industrial applications ($T_A = -40$ to $+105^{\circ}$ C)" and the products "A: Consumer applications, and D: Industrial applications".

Parameter	Aŗ	oplication
	A: Consumer applications, D: Industrial applications	G: Industrial applications
Operating ambient temperature	T _A = -40 to +85°C	T _A = -40 to +105°C
Operating mode Operating voltage range	HS (high-speed main) mode: $2.7 \text{ V} \leq \text{V}_{\text{DD}} \leq 5.5 \text{ V} \textcircled{0}1 \text{ MHz to } 32 \text{ MHz}$ $2.4 \text{ V} \leq \text{V}_{\text{DD}} \leq 5.5 \text{ V} \textcircled{0}1 \text{ MHz to } 16 \text{ MHz}$ $LS \text{ (low-speed main) mode:}$ $1.8 \text{ V} \leq \text{V}_{\text{DD}} \leq 5.5 \text{ V} \textcircled{0}1 \text{ MHz to } 8 \text{ MHz}$ $LV \text{ (low-voltage main) mode:}$ $1.6 \text{ V} \leq \text{V}_{\text{DD}} \leq 5.5 \text{ V} \textcircled{0}1 \text{ MHz to } 4 \text{ MHz}$	HS (high-speed main) mode only: $2.7~V \le V_{DD} \le 5.5~V @ 1~MHz~to~32~MHz$ $2.4~V \le V_{DD} \le 5.5~V @ 1~MHz~to~16~MHz$
High-speed on-chip oscillator clock accuracy	1.8 V \leq V _{DD} \leq 5.5 V \pm 1.0%@ T _A = -20 to +85°C \pm 1.5%@ T _A = -40 to -20°C 1.6 V \leq V _{DD} $<$ 1.8 V \pm 5.0%@ T _A = -20 to +85°C \pm 5.5%@ T _A = -40 to -20°C	$2.4 \text{ V} \le \text{V}_{DD} \le 5.5 \text{ V}$ $\pm 2.0\%$ \bigcirc T _A = +85 to +105°C $\pm 1.0\%$ \bigcirc T _A = -20 to +85°C $\pm 1.5\%$ \bigcirc T _A = -40 to -20°C
Serial array unit	UART CSI: fclk/2 (supporting 16 Mbps), fclk/4 Simplified I ² C communication	UART CSI: fclk/4 Simplified I ² C communication
IICA	Normal mode Fast mode Fast mode plus	Normal mode Fast mode
Voltage detector	Rise detection voltage: 1.67 V to 4.06 V (14 levels) Fall detection voltage: 1.63 V to 3.98 V (14 levels)	Rise detection voltage: 2.61 V to 4.06 V (8 levels) Fall detection voltage: 2.55 V to 3.98 V (8 levels)

(Remark is listed on the next page.)



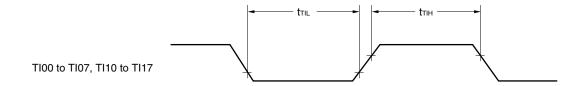
Absolute Maximum Ratings (TA = 25°C) (2/2)

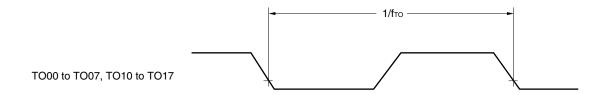
Parameter	Symbols		Conditions	Ratings	Unit
Output current, high	Іон1	Per pin	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147	-40	mA
		Total of all pins -170 mA	P00 to P04, P07, P32 to P37, P40 to P47, P102 to P106, P120, P125 to P127, P130, P140 to P145	- 70	mA
			P05, P06, P10 to P17, P30, P31, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100, P101, P110 to P117, P146, P147	-100	mA
	Іон2	Per pin	P20 to P27, P150 to P156	-0.5	mA
		Total of all pins		-2	mA
Output current, low	lo _{L1}	Per pin	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147	40	mA
		Total of all pins 170 mA	P00 to P04, P07, P32 to P37, P40 to P47, P102 to P106, P120, P125 to P127, P130, P140 to P145	70	mA
			P05, P06, P10 to P17, P30, P31, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100, P101, P110 to P117, P146, P147	100	mA
	lo _{L2}	Per pin	P20 to P27, P150 to P156	1	mA
		Total of all pins		5	mA
Operating ambient temperature	Та	In normal operati	on mode programming mode	-40 to +105	°C
	l				

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

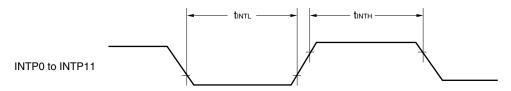
Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

TI/TO Timing

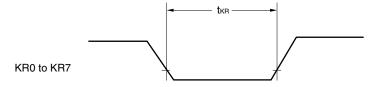




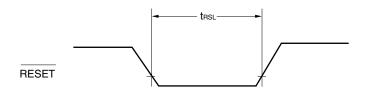
Interrupt Request Input Timing



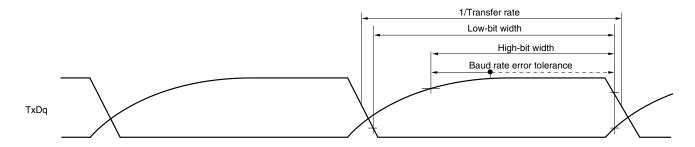
Key Interrupt Input Timing

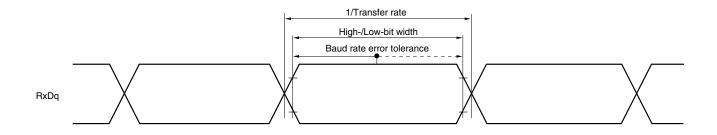


RESET Input Timing



UART mode bit width (during communication at different potential) (reference)



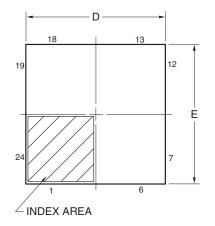


- $\begin{tabular}{ll} \textbf{Remarks 1.} & R_b[\Omega]: Communication line (TxDq) pull-up resistance, \\ & C_b[F]: Communication line (TxDq) load capacitance, V_b[V]: Communication line voltage \\ \end{tabular}$
 - **2.** q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 8, 14)
 - 3. fmck: Serial array unit operation clock frequency(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn).m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))
 - **4.** UART2 cannot communicate at different potential when bit 1 (PIOR1) of peripheral I/O redirection register (PIOR) is 1.

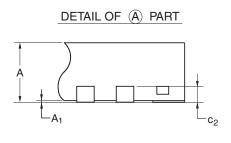
4.2 24-pin Products

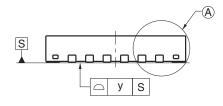
R5F1007AANA, R5F1007CANA, R5F1007DANA, R5F1007EANA R5F1017AANA, R5F1017CANA, R5F1017DANA, R5F1017EANA R5F1007ADNA, R5F1007CDNA, R5F1007DDNA, R5F1007EDNA R5F1007AGNA, R5F1007CGNA, R5F1007DGNA, R5F1007EGNA

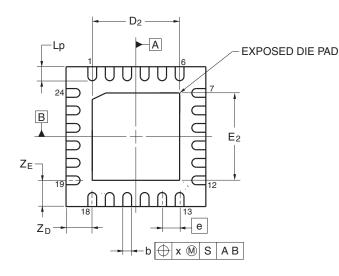
JEITA Package code	RENESAS code	Previous code	MASS(TYP.)[g]
P-HWQFN24-4x4-0.50	PWQN0024KE-A	P24K8-50-CAB-3	0.04









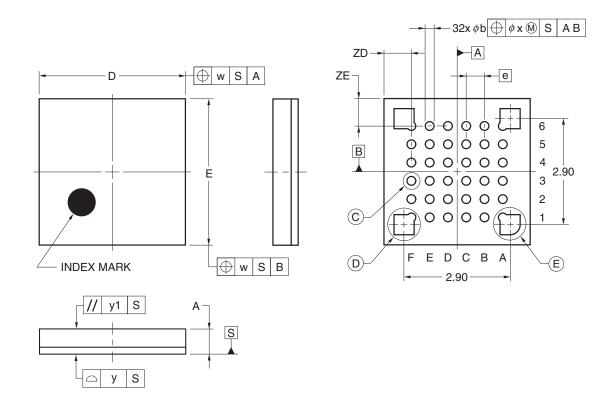


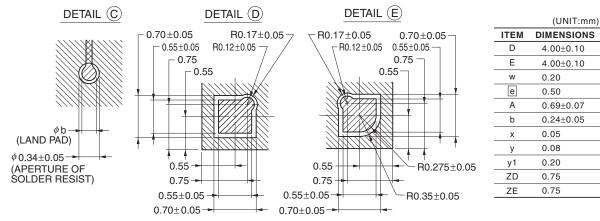
Referance	Dimens	Dimension in Millimeters		
Symbol	Min	Nom	Max	
D	3.95	4.00	4.05	
Е	3.95	4.00	4.05	
Α		_	0.80	
A ₁	0.00			
b	0.18	0.25	0.30	
е	_	0.50	_	
Lp	0.30	0.40	0.50	
х	_	_	0.05	
у		-	0.05	
Z _D		0.75		
Z _E		0.75		
C ₂	0.15	0.20	0.25	
D ₂		2.50		
E ₂	_	2.50		

4.6 36-pin Products

R5F100CAALA, R5F100CCALA, R5F100CDALA, R5F100CEALA, R5F100CFALA, R5F100CGALA R5F101CAALA, R5F101CCALA, R5F101CDALA, R5F101CEALA, R5F101CFALA, R5F101CGALA R5F100CAGLA, R5F100CCGLA, R5F100CDGLA, R5F100CEGLA, R5F100CFGLA, R5F100CGGLA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-WFLGA36-4x4-0.50	PWLG0036KA-A	P36FC-50-AA4-2	0.023





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4.10 52-pin Products

R5F100JCAFA, R5F100JDAFA, R5F100JEAFA, R5F100JFAFA, R5F100JGAFA, R5F100JHAFA, R5F100JJAFA, R5F100JKAFA, R5F100JLAFA

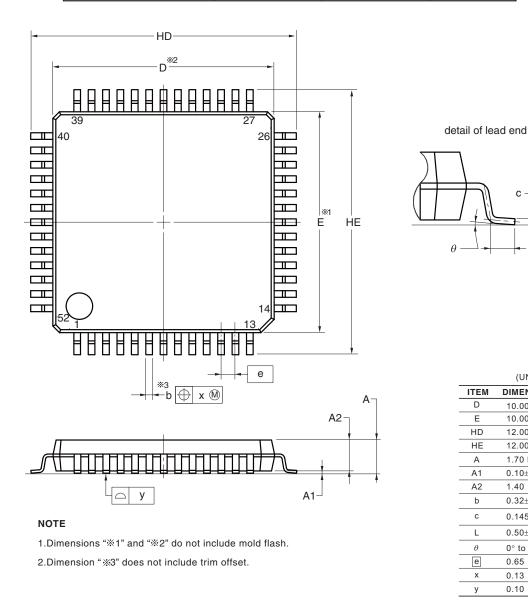
R5F101JCAFA, R5F101JDAFA, R5F101JEAFA, R5F101JFAFA, R5F101JJAFA, R5F101JJAFA, R5F101JJAFA, R5F101JAFA, R5F101JKAFA, R5F101JLAFA

R5F100JCDFA, R5F100JDDFA, R5F100JEDFA, R5F100JFDFA, R5F100JDFA, R5F100JPA, R R5F100JKDFA, R5F100JLDFA

R5F101JCDFA, R5F101JDDFA, R5F101JEDFA, R5F101JFDFA, R5F101JDFA, R5 R5F101JKDFA, R5F101JLDFA

R5F100JCGFA, R5F100JDGFA, R5F100JEGFA, R5F100JFGFA, R5F100JGGFA, R5F100JHGFA, R5F100JJGFA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-LQFP52-10x10-0.65	PLQP0052JA-A	P52GB-65-GBS-1	0.3



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(UNIT:mm)

DIMENSIONS

10.00±0.10

10.00±0.10

12.00±0.20

12.00±0.20 1.70 MAX.

 0.10 ± 0.05 1.40

0.32±0.05

 $0.50 {\pm} 0.15$

 0° to 8° 0.65

0.13 0.10

0.145±0.055

R5F100LCAFB, R5F100LDAFB, R5F100LEAFB, R5F100LFAFB, R5F100LGAFB, R5F100LHAFB, R5F100LJAFB, R5F100LKAFB, R5F100LLAFB

R5F101LCAFB, R5F101LDAFB, R5F101LEAFB, R5F101LFAFB, R5F101LGAFB, R5F101LHAFB,

R5F101LJAFB, R5F101LKAFB, R5F101LLAFB

R5F100LCDFB, R5F100LDDFB, R5F100LEDFB, R5F100LFDFB, R5F100LGDFB, R5F100LHDFB, R5F100LDFB, R5F100LKDFB, R5F100LKDFB

R5F101LCDFB, R5F101LDDFB, R5F101LEDFB, R5F101LFDFB, R5F101LGDFB, R5F101LHDFB,

R5F101LJDFB, R5F101LKDFB, R5F101LLDFB

R5F100LCGFB, R5F100LDGFB, R5F100LEGFB, R5F100LFGFB, R5F100LGGFB, R5F100LHGFB, R5F100LJGFB

	JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.)) [g]
	P-LFQFP64-10x10-0.50	PLQP0064KF-A	P64GB-50-UEU-2	0.35	
	HD — D — 48 49	33	E HE	detail of	lead end
E -	64 1 1 -ZD	17 16 e		ITEM D E HD HE A	(UNIT:mm) DIMENSIONS 10.00±0.20 10.00±0.20 12.00±0.20 12.00±0.20 160 MAX. 0.10±0.05
Œ	- b	x (M) S	A2 ¬	A2 A3 b c L Lp	1.40±0.05 0.25 0.22±0.05 0.145 +0.055 0.50 0.60±0.15
<u> </u>	Lays		A1	L1 θ e x	1.00±0.20 3°+5° 0.50 0.08

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0.08

1.25

ZD

ZΕ

NOTE

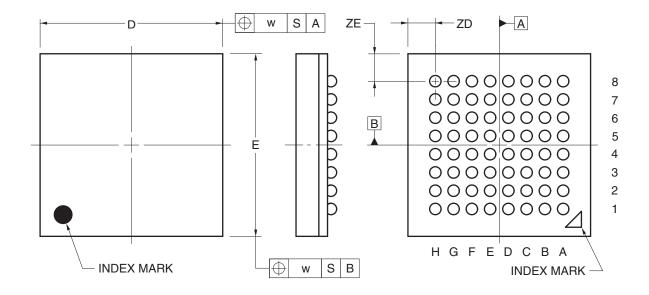
Each lead centerline is located within 0.08 mm of its true position at maximum material condition.

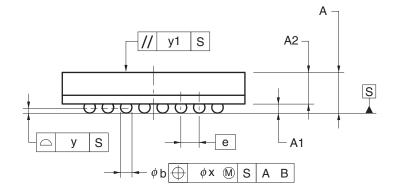
R5F100LCABG, R5F100LDABG, R5F100LEABG, R5F100LFABG, R5F100LGABG, R5F100LHABG, R5F100LJABG

R5F101LCABG, R5F101LDABG, R5F101LEABG, R5F101LFABG, R5F101LGABG, R5F101LHABG, R5F101LJABG

R5F100LCGBG, R5F100LDGBG, R5F100LEGBG, R5F100LFGBG, R5F100LGGBG, R5F100LHGBG, R5F100LJGBG

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-VFBGA64-4x4-0.40	PVBG0064LA-A	P64F1-40-AA2-2	0.03





	(UNIT:mm)
ITEM	DIMENSIONS
D	4.00±0.10
Е	4.00±0.10
W	0.15
Α	0.89±0.10
A1	0.20±0.05
A2	0.69
е	0.40
b	0.25±0.05
х	0.05
у	0.08
у1	0.20
ZD	0.60
ZE	0.60

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		Description		
Rev. Date		Page	Summary	
3.00 Aug	Aug 02, 2013	118	Modification of table in 2.6.2 Temperature sensor/internal reference voltage characteristics	
		118	Modification of table and note in 2.6.3 POR circuit characteristics	
		119	Modification of table in 2.6.4 LVD circuit characteristics	
		120	Modification of table of LVD Detection Voltage of Interrupt & Reset Mode	
		120	Renamed to 2.6.5 Power supply voltage rising slope characteristics	
		122	Modification of table, figure, and remark in 2.10 Timing Specs for Switching Flash Memory Programming Modes	
		123	Modification of caution 1 and description	
		124	Modification of table and remark 3 in Absolute Maximum Ratings (T _A = 25°C)	
		126	Modification of table, note, caution, and remark in 3.2.1 X1, XT1 oscillator characteristics	
		126	Modification of table in 3.2.2 On-chip oscillator characteristics	
		127	Modification of note 3 in 3.3.1 Pin characteristics (1/5)	
		128	Modification of note 3 in 3.3.1 Pin characteristics (2/5)	
		133	Modification of notes 1 and 4 in (1) Flash ROM: 16 to 64 KB of 20- to 64-pin products (1/2)	
		135	Modification of notes 1, 5, and 6 in (1) Flash ROM: 16 to 64 KB of 20- to 64-pin products (2/2)	
		137	Modification of notes 1 and 4 in (2) Flash ROM: 96 to 256 KB of 30- to 100-pin products (1/2)	
		139	Modification of notes 1, 5, and 6 in (2) Flash ROM: 96 to 256 KB of 30- to 100-pin products (2/2)	
		140	Modification of (3) Peripheral Functions (Common to all products)	
		142	Modification of table in 3.4 AC Characteristics	
		143	Addition of Minimum Instruction Execution Time during Main System Clock Operation	
		143	Modification of figure of AC Timing Test Points	
		143	Modification of figure of External System Clock Timing	
		145	Modification of figure of AC Timing Test Points	
		145	Modification of description, note 1, and caution in (1) During communication at same potential (UART mode)	
		146	Modification of description in (2) During communication at same potential (CSI mode)	
		147	Modification of description in (3) During communication at same potential (CSI mode)	
		149	Modification of table, note 1, and caution in (4) During communication at same potential (simplified I ² C mode)	
		151	Modification of table, note 1, and caution in (5) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode) (1/2)	
		152 to 154	Modification of table, notes 2 to 6, caution, and remarks 1 to 4 in (5) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode) (2/2)	
		155	Modification of table in (6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (1/3)	
		156	Modification of table and caution in (6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (2/3)	
		157, 158	Modification of table, caution, and remarks 3 and 4 in (6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (3/3)	
		160, 161	Modification of table and caution in (7) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode)	